

	Type	Hits	Search Text
1	BRS	2	"6422921"
2	BRS	248673	abrasive polishing
3	BRS	492844	pad pads
4	BRS	16634	(abrasive polishing) with (pad pads)
5	BRS	1	(heat adj sensitive adj adhesive adj tape) and ((abrasive polishing) with (pad pads))
6	BRS	2532	heat adj sensitive adj adhesive
7	BRS	3	((abrasive polishing) with (pad pads)) and (heat adj sensitive adj adhesive )
8	BRS	2	((abrasive polishing) with (pad pads)) and (heat adj sensitive adj adhesive )) not ((heat adj sensitive adj adhesive adj tape) and ((abrasive polishing) with (pad pads)))
9	BRS	299	heat adj sensitive adj adhesive
10	BRS	6	heat adj sensitive adj adhesive adj tape
11	BRS	84970	pad pads
12	BRS	43374	abrasive polishing
13	BRS	1444	(pad pads) with (abrasive polishing)
14	BRS	0	((pad pads) with (abrasive polishing)) and (heat adj sensitive adj adhesive )
15	BRS	62187	adhesive adj tape
16	BRS	242	((abrasive polishing) with (pad pads)) and (adhesive adj tape)
17	BRS	2	((abrasive polishing) with (pad pads)) and (adhesive adj tape)) and (heat adj sensitive)

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:23		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:25		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:25		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:40		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:23		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:25		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:24		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:24		
9	USOCR	2004/04/07 12:25		
10	USOCR	2004/04/07 12:25		
11	USOCR	2004/04/07 12:25		
12	USOCR	2004/04/07 12:25		
13	USOCR	2004/04/07 12:25		
14	USOCR	2004/04/07 12:25		
15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:28		
16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:29		
17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:30		

	Type	Hits	Search Text
18	BRS	21	intelimer
19	BRS	1	intelimer and ((abrasive polishing) with (pad pads))
20	BRS	5867	top adj ring
21	BRS	1	(heat adj sensitive adj adhesive adj tape) and (top adj ring)
22	BRS	1	(top adj ring) and (heat adj sensitive adj adhesive )
23	BRS	0	(top adj ring) and (head adj sensitive)
24	BRS	13	(top adj ring) and (heat adj sensitive)
25	BRS	2145	backing adj film
26	BRS	2230124	backing al26 and l4dj film
27	BRS	1	(backing adj film) and (heat adj sensitive adj adhesive adj tape)
28	BRS	5	temperature adj sensitive adj adhesive adj tape
29	BRS	1247	((abrasive polishing) with (pad pads)) same (adhesive adhere glue glued gluing)) and (wafer wafers substrate substrates semiconductor semiconductors)
30	BRS	1718	((abrasive polishing) with (pad pads)) same (adhesive adhere glue glued gluing)
31	BRS	1194	((abrasive polishing) with (pad pads)) same (adhesive adhere glue glued gluing)) not (pressure adj sensitive)
32	BRS	707	451/\$.ccls. and (((abrasive polishing) with (pad pads)) same (adhesive adhere glue glued gluing)) and (wafer wafers substrate substrates semiconductor semiconductors))

	DBs	Time Stamp	Comments	Error Definition
18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:30		
19	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:31		
20	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:31		
21	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:31		
22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:32		
23	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:32		
24	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:33		
25	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:33		
26	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:34		
27	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:34		
28	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:34		
29	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:41		
30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:44		
31	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:44		
32	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:44		

	Type	Hits	Search Text
33	BRS	572	451/\$.ccls. and (((abrasive polishing) with (pad pads)) same (adhesive adhere glue glued gluing)) not (pressure adj sensitive))
34	BRS	64	heat adj sensitive adj adhesive adj tape
35	BRS	22827	(abrasive polishing) with (pad pads cloth cloths)
36	BRS	2533	(heat condition) adj sensitive adj adhesive
37	BRS	9	((abrasive polishing) with (pad pads cloth cloths)) and ((heat condition) adj sensitive adj adhesive)
38	BRS	2145	backing adj film
39	BRS	11	((heat condition) adj sensitive adj adhesive) and (backing adj film)
40	BRS	43606	double adj sided
41	BRS	11	((heat condition) adj sensitive adj adhesive) same (double adj sided)
42	BRS	0	((abrasive polishing) with (pad pads cloth cloths)) and (((heat condition) adj sensitive adj adhesive) and (double adj sided))
43	BRS	1046394	carrier
44	BRS	134	(backing adj film) with carrier
45	BRS	4	((backing adj film) with carrier ) and ((heat condition) adj sensitive adj adhesive)
46	BRS	68	((heat condition) adj sensitive adj adhesive) and (double adj sided)
47	BRS	82	(backing adj film) near3 carrier
48	BRS	39	((backing adj film) near3 carrier ) with (adhesive adhere adhering glue glued gluing)

	DBs	Time Stamp	Comments	Error Definition
33	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:45		
34	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:45		
35	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:55		
36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 12:55		
37	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:26		
38	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:00		
39	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:23		
40	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:24		
41	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:25		
42	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:25		
43	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:26		
44	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:39		
45	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:26		
46	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:30		
47	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:39		
48	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 13:40		